

MA2SP05

Silicon epitaxial planar type

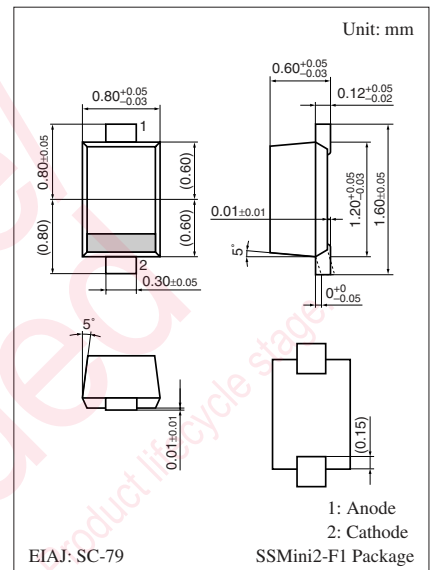
For high frequency attenuator

■ Features

- High performance forward current I_F controlled forward dynamic resistance r_f
- Small terminal capacitance C_t
- Miniature package and surface mounting type

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

| Parameter | Symbol | Rating | Unit |
|----------------------|-----------|-------------|------------------|
| Reverse voltage | V_R | 60 | V |
| Forward current | I_F | 50 | mA |
| Junction temperature | T_j | 150 | $^\circ\text{C}$ |
| Storage temperature | T_{stg} | -55 to +150 | $^\circ\text{C}$ |

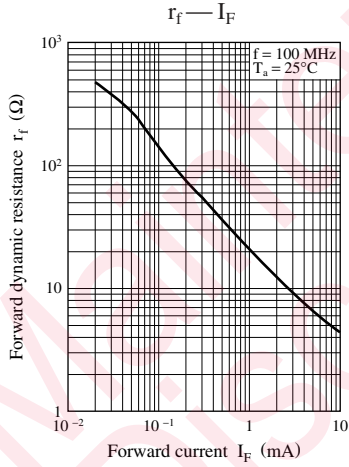
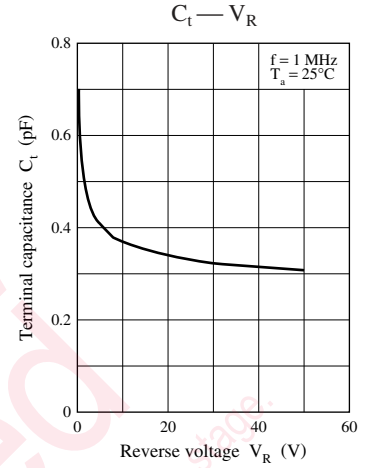
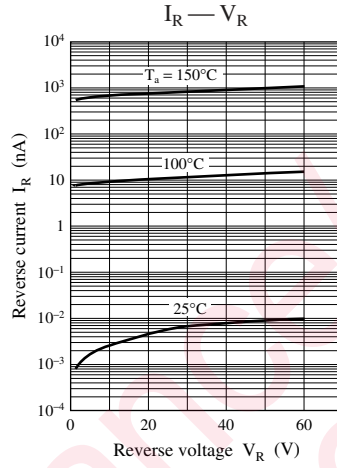
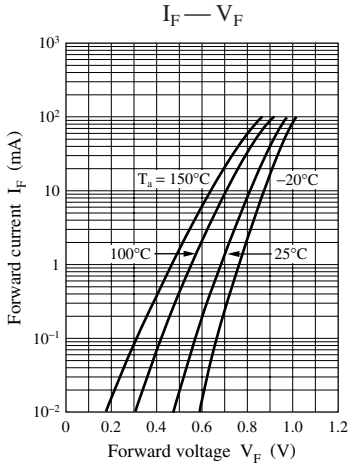


Marking Symbol: 6P

■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

| Parameter | Symbol | Conditions | Min | Typ | Max | Unit |
|----------------------------|--------|--|-----|-----|-----|----------|
| Forward voltage | V_F | $I_F = 10 \text{ mA}$ | | | 1.0 | V |
| Reverse current | I_R | $V_R = 60 \text{ V}$ | | | 100 | nA |
| Terminal capacitance | C_t | $V_R = 0 \text{ V}, f = 1 \text{ MHz}$ | | | 2.4 | pF |
| Forward dynamic resistance | r_f | $I_F = 10 \text{ mA}, f = 100 \text{ MHz}$ | | | 5.5 | Ω |

Note) Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.



Maintenance/Discontinued includes following four Product lifecycle stages:
 planned maintenance type
 maintenance type
 planned discontinued type
 discontinued type
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